

LINEAR TECHNOLOGY MATERIALS DECLARATION

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(Engineering Calculation)

TSSOP Exp. Pad

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TOTAL MASS (g) : 0.070665

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------------|----------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|----------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.005437 | 1000000 | 76940.5859375 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000000 | 0 | 0 | | |
| Lead Frame | Cu | Copper (Cu) | 7440-50-8 | 0.025576 | 975000 | 361933.5 | | |
| | | Iron (Fe) | 7439-89-6 | 0.000630 | 24000 | 8915.31640625 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000008 | 300 | 113.210357666 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000018 | 700 | 254.723297119 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| Lead Frame Total: | | | | 0.026232 | 1000000 | 371216.78125 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.002364 | 1000000 | 33452.3828125 | | |
| | | External Plating Total: | | | | 0.002364 | 1000000 | 33452.3828125 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.001030 | 1000000 | 14575.8339844 | | |
| Internal Plating Total: | | | | 0.001030 | 1000000 | 14575.8339844 | | |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.001372 | 750000 | 19415.5761719 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000457 | 250000 | 6467.14160156 | | |
| Die Attach Total: | | | | 0.001829 | 1000000 | 25882.7167969 | | |
| Encapsulation | MULTI-AROMATIC RESIN Br/Sb FREE | Resin (EP) | | 0.004875 | 150000 | 68987.5625 | | |
| | | Bromine (Br) | 40039-93-8 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.026650 | 820000 | 377132 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.000000 | 0 | 0 | | |
| | | Metal Hydroxide | | 0.000813 | 25000 | 11505.0029297 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.000163 | 5000 | 2306.66113281 | | |
| | | Encapsulation Total: | | | | 0.032501 | 1000000 | 459931.25 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.001272 | 1000000 | 18000.4453125 | | |
| | | | | | TOTAL MASS (g) : | 0.070665 | | |